



Material Content Data Sheet



Sales Product Name				BSZ086P03NS3E G		Issued		19. July 2018	
MA#				MA001413074					
Package				PG-TSDSON-8-2		Weight*		40.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.835	4.56	4.56	45635	45635	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		52		
	non noble metal	zinc	7440-66-6	0.008	0.02		208		
	non noble metal	iron	7439-89-6	0.168	0.42		4170		
wire	non noble metal	copper	7440-50-8	6.808	16.93	17.38	169313	173743	
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	885	885	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.09		909	
	plastics	epoxy resin	-	1.882	4.68		46818		
	inorganic material	silicondioxide	60676-86-0	16.357	40.70	45.47	406817	454544	
leadfinish	non noble metal	tin	7440-31-5	0.392	0.97	0.97	9749	9749	
plating	noble metal	silver	7440-22-4	0.963	2.39	2.39	23940	23940	
solder	non noble metal	tin	7440-31-5	0.037	0.09		915		
	noble metal	silver	7440-22-4	0.046	0.11		1144		
	non noble metal	lead	7439-92-1	1.758	4.37	4.57	43713	45772	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		107		
	non noble metal	iron	7439-89-6	0.086	0.21		2145		
	non noble metal	copper	7440-50-8	3.501	8.71	8.93	87077	89356	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		47		
	non noble metal	zinc	7440-66-6	0.008	0.02		188		
	non noble metal	iron	7439-89-6	0.151	0.38		3753		
	non noble metal	copper	7440-50-8	6.127	15.24	15.64	152388	156376	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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